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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/546,174	04/11/2000	Chih-Chien Liu	JIA 462C1	4793	
25235 7	7590 09/08/2006		EXAMINER		
HOGAN & HARTSON LLP			SERGENT, RABON A		
ONE TABOR	CENTER, SUITE 1500				
1200 SEVENTEENTH ST			ART UNIT	PAPER NUMBER	
DENVER, CO 80202			1711		

1711
DATE MAILED: 09/08/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

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		Application No.	Applicant(s)				
		09/546,174	LIU ET AL.				
	Office Action Summary	Examiner	Art Unit				
		Rabon Sergent	1711				
Period fo	The MAILING DATE of this communication						
		DIVIQUET TO EVOIDE 2 MON	TU/C) OD TUIDTV /30) DAVC				
WHIC - Exter after - If NO - Failu Any	ORTENED STATUTORY PERIOD FOR RECHEVER IS LONGER, FROM THE MAILING asions of time may be available under the provisions of 37 CFF SIX (6) MONTHS from the mailing date of this communication of period for reply is specified above, the maximum statutory periore to reply within the set or extended period for reply will, by state to reply within the set or extended period for reply will, by state to reply within the set or extended period for reply will, by state to the maximum and the maximum a	G DATE OF THIS COMMUNICAT R 1.136(a). In no event, however, may a reply l riod will apply and will expire SIX (6) MONTHS atute, cause the application to become ABAND	FION. be timely filed from the mailing date of this communication. FONED (35 U.S.C. § 133).				
Status							
1)⊠	Responsive to communication(s) filed on 19	9 June 2006.					
		This action is non-final.					
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
	closed in accordance with the practice under	er <i>Ex par</i> te Quayle, 1935 C.D. 11	, 453 O.G. 213.				
Dispositi	ion of Claims						
4)🖂	Claim(s) 50-69,72-74,78-88 and 90-102 is/a	are pending in the application.					
	4a) Of the above claim(s) is/are without	drawn from consideration.					
5)□	Claim(s) is/are allowed.						
	☑ Claim(s) <u>50-69, 72-74, 78-88, and 90-102</u> is/are rejected.						
8)∟_	Claim(s) are subject to restriction and	d/or election requirement.					
Applicati	on Papers						
9)□ .	The specification is objected to by the Exam	iner.					
	The drawing(s) filed on is/are: a) \square a	-					
	Applicant may not request that any objection to t						
	Replacement drawing sheet(s) including the com						
11)	The oath or declaration is objected to by the	Examiner. Note the attached On	lice Action or form PTO-152.				
Priority u	ınder 35 U.S.C. § 119						
	Acknowledgment is made of a claim for fore ☐ All b)☐ Some * c)☐ None of:	ign priority under 35 U.S.C. § 119	9(a)-(d) or (f).				
	1. Certified copies of the priority docume						
	2. Certified copies of the priority documents have been received in Application No						
	3. Copies of the certified copies of the p		eived in this National Stage				
* 0	application from the International Bureau (PCT Rule 17.2(a)).						
· 3	ee the attached detailed Office action for a l	ist of the certified copies not rece	aived.				
Attachment	(s)						
	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948)	4) Interview Summ Paper No(s)/Mai	ary (PTO-413)				
	nation Disclosure Statement(s) (PTO/SB/08)	5) 🔲 Notice of Inform	al Patent Application				
Paper	No(s)/Mail Date	6) 🔲 Other:					

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1. Claims 80-93, 99, and 102 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

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The language, "substantially one thickness", renders the claims indefinite, because it cannot be determined what degree of variation in thickness is permitted by the word, "substantially". Applicants have not provided any guidance that would permit one to determine how "substantially" is to be interpreted.

2. Claims 50-61, 80-100, and 102 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

Despite applicants' remarks, adequate support has not been found within the specification for "uniform thickness" within claim 50 and "having substantially one thickness" within claim 80. Applicants' cited disclosures within pages 10 and 11 have been considered; however, it is not seen that these passages disclose a uniform thickness or define a degree of uniformity. Furthermore, no definition has been provided for "substantially"; therefore, it cannot be determined what degree of variance is permitted by the language.

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

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This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

4. Claims 50-69, 72-74, 78-88, and 90-102 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tobben et al. ('126) in view of JP 8-288285.

Tobben et al. disclose the production of semiconductor devices containing electrically conductive wires on a substrate, wherein the method comprises the etching of a layered composite comprising a substrate layer, a titanium/titanium nitride layer (corresponding to applicants' surface layer of claims 61 and 84), an aluminum wiring line layer, an antireflective coating layer of titanium/titanium nitride (corresponding to applicants' conductive layer of claim 50, applicants' protective layer of claim 61, and applicants' antireflective coating of claim 80), and a cap layer. See figures and columns 2-4, especially column 2, lines 32-46 and column 3, lines 6+. Tobben et al. additionally disclose at column 3, lines 11-24 and Figures 3-5 that a photoresist layer is applied to the cap layer. Tobben et al. further teach at column 4, lines 10-26 that if an additional metalization layer is to be used, then a layer of dielectric material is deposited over the surface of the structure and within the grooves between the wiring lines. Tobben et al. additionally teach that this layer may be formed by depositing silicon dioxide using high density plasma deposition techniques. The subject matter of claims 53 and 63 is considered

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to be a characteristic of the disclosed deposition process. The subject matter of claims 54 and 64 is disclosed at column 3, line 13. The subject matter of claim 55 is disclosed by the figures. The subject matter of claim 59 is considered to be a characteristic of the etching process, given that the degree of the etching away of the corners is not specified. The subject matter of claims 60 and 69 is considered to be a characteristic of the disclosed deposition process. Similarly, the subject matter of claims 86 and 87 is considered to be a characteristic of the disclosed process. The subject matter of claims 65-68 is disclosed within column 4, lines 5-18. The claimed subject matter pertaining to the differences in dielectric constants between respective layers is considered to be disclosed by Tobben et al. in that Tobben et al. disclose that these layers are formed from different materials; therefore, it follows that the respective layers would have different dielectric constants and the argued graded index of refraction.

- 5. With respect to claims 56-58 and 87, while Tobben et al. specifically disclose rectangular gaps or grooves, patentees fail to recite other cross-sectional shapes for the grooves, such as trapezoidal or triangular cross-sections; however, the position is taken that the production of such shapes by controlling the parameters of the etching process was known and conventional at the time of invention. Accordingly, the selection of such cross-sections amounts to an obvious design choice and the implementation of such choices requires only the control of result effective variables.
- 6. Tobben et al. are silent with respect to applicants' adaptation of the cap layer as it pertains to destructive interference or graded index of refraction (claims 50, 61, and 80), applicants' use of the cap layer as a hard mask (claims 51, 62, and 82), and applicants' use of a different plasma process after the initial use of a HDPCVD process (claim 80). However, each

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of these features was known within the semiconductor processing art and/or etching art at the time of invention. This position is supported by the teachings of JP 8-288285. Firstly, JP 8-288285 discloses at pages 10 and 11 of the translation that the composition (optical constant) and thickness of the protection insulating film (cap layer) are optimized so that during photolithography, an interference effect is created to minimize reflection. The position is further taken that this disclosure also renders applicants' graded index of refraction limitations obvious, as the disclosed modification would also modify the refractive properties of the modified layer. Secondly, JP 8-288285 discloses at pages 10 and 12 that the cap layer can be used as a mask for patterning the wiring lines. Therefore, the position is taken that it would have been obvious to modify the cap layer of Tobben et al. in accordance with these known techniques so as to yield a more efficient process and higher quality product. One would have expected that the greater control of the patterning or masking of the layers afforded by these modifications would have yielded a product having a more precise wiring line pattern with less defects. Lastly, JP 8-288285 discloses at page 20 and page 25, lines 14-19 that the planarizing layers can be applied using multiple deposition steps or processes. Therefore, in accordance with the teachings of the secondary reference, the position is taken that it would have been obvious to subsequently use a deposition process different from the initially used HDPCVD process, so as to obtain an optimized or more finely planarized surface.

7. Applicants have essentially argued that Tobben et al. fail to disclose a cap layer having applicants' claimed thickness requirements, because the planarization layer of Tobben et al. is different from the claimed cap layer. This argument is not found persuasive for the following reasons. Firstly, as aforementioned, applicants have failed to provide an adequate disclosure of a

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cap layer of uniform thickness or a cap layer having substantially one thickness; therefore, it cannot be clearly determined just what variances in thickness are permitted or how uniform the layer must be. Therefore, it is unclear if the language, as claimed, distinguishes from the disclosed layer, as argued by applicants. Secondly, assuming that there is adequate definition to determine that the claimed cap layer is truly of uniform thickness, applicants have not clearly established that Tobben et al. fail to disclose such a cap layer of uniform thickness. Applicants' attention is directed to cap layer 16b within Figure 2A and disclosed at column 3, lines 9-20 of Tobben et al. From the figure and disclosure, one of ordinary skill would clearly conclude that this layer is of a uniform thickness adequate to meet applicants' claims. In summation, given the teachings within Tobben et al., applicants have failed to establish that the argued features of the claims are neither disclosed by the primary reference nor rendered obvious for the aforementioned reasons by the combined teachings of the references.

8. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event,

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however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication should be directed to R. Sergent at telephone number (571) 272-1079.

RABON SERGENT PRIMARY EXAMINER

R. Sergent September 5, 2006